

# PMEG060T080CLPE

60 V, 2 x 4 A dual common cathode low leakage current Trench MEGA Schottky barrier rectifier

27 April 2020 Product data sheet

## 1. General description

Trench Maximum Efficiency General Application (MEGA) dual Schottky barrier rectifier in common cathode configuration encapsulated in a CFP15B (SOT1289B) power and flat lead Surface-Mounted Device (SMD) plastic package.

## 2. Features and benefits

- Reverse voltage: V<sub>R</sub> ≤ 60 V
- Forward current: I<sub>F</sub> ≤ 4 A (per diode)
- Low forward voltage
- Low leakage current due to Trench MEGA Schottky technology
- Power and flat lead SMD plastic package
- · Package height typical 0.95 mm
- · High power capability due to clip-bond technology
- AEC-Q101 qualified

## 3. Applications

- Low voltage rectification
- · High efficiency DC-to-DC conversion
- · Switch mode power supply
- Reverse polarity protection
- Low power consumption applications
- Freewheeling applications

### 4. Quick reference data

Table 1. Quick reference data

| Symbol             | Parameter               | Conditions   |     | Min | Тур  | Max | Unit |
|--------------------|-------------------------|--|-----|-----|------|-----|------|
| Per diode (u       | inless otherwise specif | ied)   |     |     |      | '   | ·    |
| I <sub>F(AV)</sub> | average forward current | $\delta$ = 0.5; square wave; f = 20 kHz; $T_{sp} \le$ 160 °C |     | -   | -    | 4   | Α    |
| $V_R$              | reverse voltage         | T <sub>j</sub> = 25 °C                                       |     | -   | -    | 60  | V    |
| V <sub>F</sub>     | forward voltage         | I <sub>F</sub> = 4 A; T <sub>j</sub> = 25 °C                 | [1] | -   | 580  | 660 | mV   |
| I <sub>R</sub>     | reverse current         | V <sub>R</sub> = 10 V; T <sub>j</sub> = 25 °C                | [1] | -   | 0.14 | 0.9 | μA   |
|                    |                         | V <sub>R</sub> = 60 V; T <sub>j</sub> = 25 °C                | [1] | -   | 0.3  | 1.8 | μΑ   |

[1] Very short pulse, in order to maintain a stable junction temperature.



## 5. Pinning information

#### **Table 2. Pinning information**

| Pin | Symbol | Description     | Simplified outline | Graphic symbol  |
|-----|--------|-----------------|--------------------|-----------------|
| 1   | A1     | anode (diode 1) | 5                  | CC              |
| 2   | A2     | anode (diode 2) |                    |                 |
| 3   | CC     | common cathode  | CFP15B (SOT1289B)  | A1 A2 006aab034 |

## 6. Ordering information

#### **Table 3. Ordering information**

| Type number     | Package |  |          |  |  |  |  |
|-----------------|---------|--|----------|--|--|--|--|
|                 | Name    | Description  | Version  |  |  |  |  |
| PMEG060T080CLPE | CFP15B  | plastic, thermal enhanced ultra thin SMD package; 3 leads; 2.13 mm pitch; $5.8 \times 4.3 \times 0.95$ mm body | SOT1289B |  |  |  |  |

## 7. Marking

#### Table 4. Marking codes

| Type number     | Marking code |
|-----------------|--------------|
| PMEG060T080CLPE | 060T L08C    |

## 8. Limiting values

### Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC60134).

| Symbol             | Parameter                              | Conditions   |     | Min | Max  | Unit |
|--------------------|--|--|-----|-----|------|------|
| Per diode (unle    | ss otherwise specified)                |  |     |     |      |      |
| $V_R$              | reverse voltage                        | T <sub>j</sub> = 25 °C   |     | -   | 60   | V    |
| I <sub>F</sub>     | forward current                        | δ = 1; T <sub>sp</sub> ≤ 156 °C  |     | -   | 5.7  | А    |
| I <sub>F(AV)</sub> | average forward current                | $\delta$ = 0.5; square wave; f = 20 kHz; $T_{sp} \le$ 160 °C                         |     | -   | 4    | Α    |
| I <sub>FSM</sub>   | non-repetitive peak<br>forward current | $t_p$ = 8.3 ms; half sine wave; $T_{j(init)}$ = 25 °C                                |     | -   | 80   | Α    |
|                    |  | t <sub>p</sub> = 8.3 ms; half sine wave; per device;<br>T <sub>j(init)</sub> = 25 °C |     | -   | 150  | Α    |
| Per device, one    | diode loaded                           |  |     |     |      |      |
| P <sub>tot</sub>   | total power dissipation                | T <sub>amb</sub> ≤ 25 °C   | [1] | -   | 1.66 | W    |
|                    |  |  | [2] | -   | 2.15 | W    |
| T <sub>j</sub>     | junction temperature                   |  |     | -   | 175  | °C   |
| T <sub>amb</sub>   | ambient temperature                    |  |     | -55 | 175  | °C   |
| T <sub>stg</sub>   | storage temperature                    |  |     | -65 | 175  | °C   |

- Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated and standard footprint.
- [2] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for cathode 1 cm<sup>2</sup>.

## 9. Thermal characteristics

**Table 6. Thermal characteristics** 

| Symbol               | Parameter  | Conditions  |         | Min | Тур | Max | Unit |
|----------------------|--|-------------|---------|-----|-----|-----|------|
| Per device, one      | e diode loaded                                   |             |         |     |     |     |      |
| R <sub>th(j-a)</sub> | thermal resistance from junction to ambient      | in free air | [1] [2] | -   | -   | 90  | K/W  |
|                      |  |             | [1] [3] | -   | -   | 70  | K/W  |
| $R_{th(j-sp)}$       | thermal resistance from junction to solder point |             | [4]     | -   | -   | 7   | K/W  |

- [1] For Schottky barrier diodes thermal runaway has to be considered, as in some applications the reverse power losses P<sub>R</sub> are a significant part of the total power losses.
- [2] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.
- Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for cathode 1 cm<sup>2</sup>.
- [4] Soldering point of cathode tab.

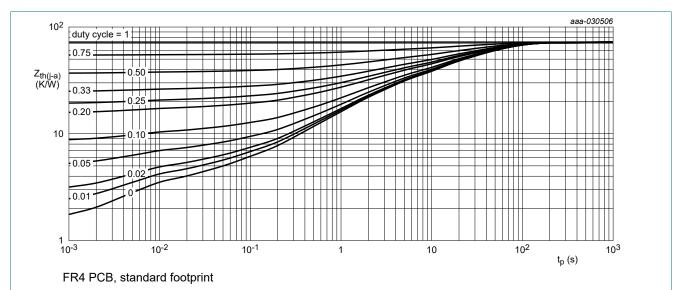


Fig. 1. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values

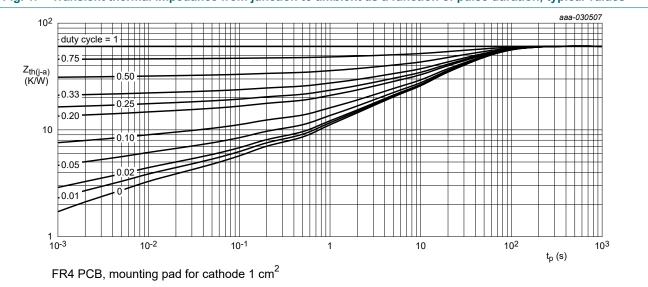


Fig. 2. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values

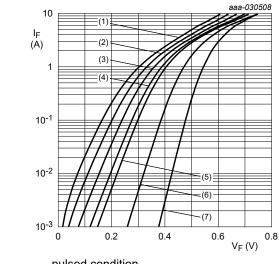
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## 10. Characteristics

**Table 7. Characteristics** 

| Symbol          | Parameter                           | Conditions   |     | Min | Тур  | Max | Unit |
|-----------------|-------------------------------------|--|-----|-----|------|-----|------|
| Per diode (ı    | unless otherwise specified          | 1)   |     |     |      |     |      |
| $V_{(BR)R}$     | reverse breakdown voltage           | I <sub>R</sub> = 1 mA; T <sub>j</sub> = 25 °C  | [1] | 60  | -    | -   | V    |
| V <sub>F</sub>  | forward voltage                     | I <sub>F</sub> = 0.5 A; T <sub>j</sub> = 25 °C   | [1] | -   | 440  | 510 | mV   |
|                 |                                     | I <sub>F</sub> = 1 A; T <sub>j</sub> = 25 °C   | [1] | -   | 470  | 540 | mV   |
|                 |                                     | I <sub>F</sub> = 4 A; T <sub>j</sub> = 25 °C   | [1] | -   | 580  | 660 | mV   |
|                 |                                     | I <sub>F</sub> = 4 A; T <sub>j</sub> = -40 °C  | [1] | -   | 630  | 720 | mV   |
|                 |                                     | I <sub>F</sub> = 4 A; T <sub>j</sub> = 125 °C  | [1] | -   | 520  | 610 | mV   |
| I <sub>R</sub>  | reverse current                     | V <sub>R</sub> = 10 V; T <sub>j</sub> = 25 °C  | [1] | -   | 0.14 | 0.9 | μΑ   |
|                 |                                     | V <sub>R</sub> = 40 V; T <sub>j</sub> = 25 °C  | [1] | -   | 0.18 | 1.2 | μΑ   |
|                 |                                     | V <sub>R</sub> = 60 V; T <sub>j</sub> = 25 °C  | [1] | -   | 0.3  | 1.8 | μΑ   |
|                 |                                     | V <sub>R</sub> = 60 V; T <sub>j</sub> = 125 °C   | [1] | -   | 0.5  | 3   | mA   |
| C <sub>d</sub>  | diode capacitance                   | V <sub>R</sub> = 1 V; f = 1 MHz; T <sub>j</sub> = 25 °C  |     | -   | 560  | -   | pF   |
|                 |                                     | $V_R = 10 \text{ V}; f = 1 \text{ MHz}; T_j = 25 ^{\circ}\text{C}$   |     | -   | 180  | -   | pF   |
| t <sub>rr</sub> | reverse recovery time step recovery | $I_F = 0.5 \text{ A}; I_R = 0.5 \text{ A}; I_{R(meas)} = 0.1 \text{ A};$<br>$T_j = 25 \text{ °C}$            |     | -   | 17   | -   | ns   |
|                 | reverse recovery time ramp recovery | $dI_F/dt = 200 \text{ A/}\mu\text{s}; I_F = 6 \text{ A}; V_R = 26 \text{ V};$<br>$T_j = 25 ^{\circ}\text{C}$ |     | -   | 11   | -   | ns   |
| $V_{FRM}$       | peak forward recovery voltage       | $I_F = 0.5 \text{ A}; dI_F/dt = 20 \text{ A/}\mu\text{s}; T_j = 25 ^{\circ}\text{C}$                         |     | -   | 460  | -   | mV   |

<sup>[1]</sup> Very short pulse, in order to maintain a stable junction temperature.



pulsed condition

(1)  $T_i = 175 \,^{\circ}C$ 

 $(2) T_i = 150 °C$ 

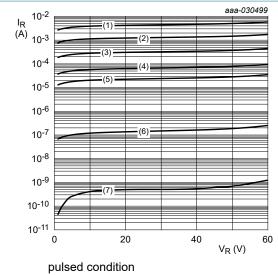
(3)  $T_j = 125 \,^{\circ}\text{C}$ 

 $(4) T_j = 100 °C$ 

(5)  $T_j = 85 ^{\circ}C$ (6)  $T_i = 25 ^{\circ}C$ 

(7)  $T_i = -40$  °C

Fig. 3. Forward current as a function of forward voltage; typical values



(1)  $T_i = 175 \,^{\circ}C$ 

 $(2) T_i = 150 °C$ 

 $(3) T_j = 125 °C$ 

 $(4) T_j = 100 °C$ 

(5)  $T_j = 85 ^{\circ}C$ (6)  $T_i = 25 ^{\circ}C$ 

 $(7) T_{i} = -40 ^{\circ}C$ 

Fig. 4. Reverse current as a function of reverse voltage; typical values

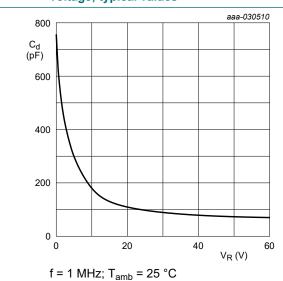
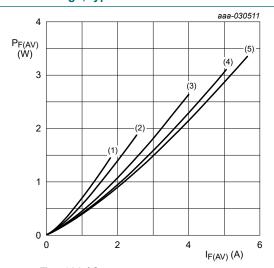


Fig. 5. Diode capacitance as a function of reverse voltage; typical values



 $T_j = 100 \,^{\circ}\text{C}$ (1)  $\delta = 0.1$ 

 $(2) \delta = 0.2$ 

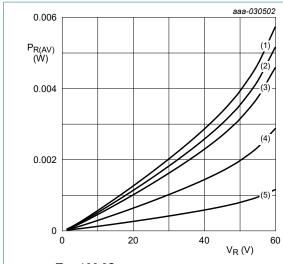
 $(3) \delta = 0.5$ 

 $(3) \delta = 0.3$  $(4) \delta = 0.8$ 

(5)  $\delta = 1$ ; DC

Fig. 6. Average forward power dissipation as a function of average forward current; typical values

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 $T_j = 100 \, ^{\circ}C$ 

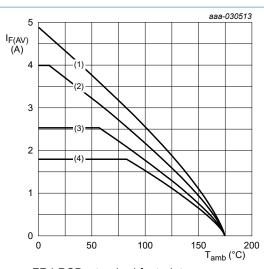
 $(1) \delta = 1; DC$ 

 $(2) \delta = 0.9$ 

 $(3) \delta = 0.8$  $(4) \delta = 0.5$ 

 $(5) \delta = 0.2$ 

Fig. 7. Average reverse power dissipation as a function of reverse voltage; typical values



FR4 PCB, standard footprint

T<sub>i</sub> = 175 °C

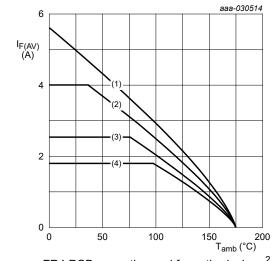
 $(1) \delta = 1$ ; DC

(2)  $\delta = 0.5$ ; f = 20 kHz

(3)  $\delta = 0.2$ ; f = 20 kHz

(4)  $\delta = 0.1$ ; f = 20 kHz

Fig. 8. Average forward current as a function of ambient temperature; typical values



FR4 PCB, mounting pad for cathode 1 cm<sup>2</sup>

T<sub>i</sub> = 175 °C

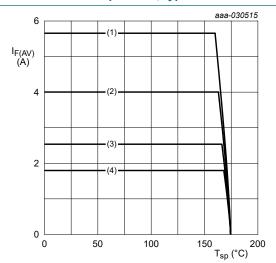
(1)  $\delta = 1$ ; DC

(2)  $\delta = 0.5$ ; f = 20 kHz

(3)  $\delta = 0.2$ ; f = 20 kHz

(4)  $\delta = 0.1$ ; f = 20 kHz

Fig. 9. Average forward current as a function of ambient temperature; typical values



 $T_i = 175 \,{}^{\circ}\text{C}$ 

 $(1) \delta = 1; DC$ 

(2)  $\delta$  = 0.5; f = 20 kHz

(3)  $\delta = 0.2$ ; f = 20 kHz

(4)  $\delta = 0.1$ ; f = 20 kHz

Fig. 10. Average forward current as a function of solder point temperature; typical values

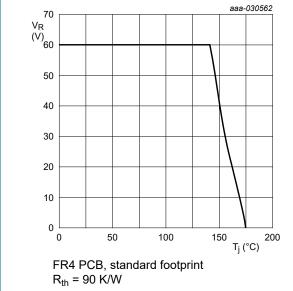
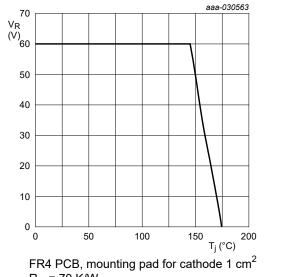
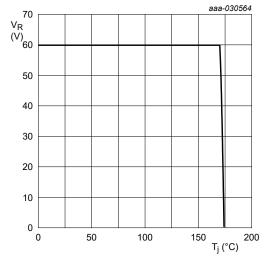


Fig. 11. Derated maximum reverse voltage as a function | Fig. 12. Derated maximum reverse voltage as a function of junction temperature; typical values



 $R_{th} = 70 \text{ K/W}$ 

of junction temperature; typical values



Soldering point of cathode tab  $R_{th} = 7 \text{ K/W}$ 

Fig. 13. Derated maximum reverse voltage as a function of junction temperature; typical values

## 11. Test information

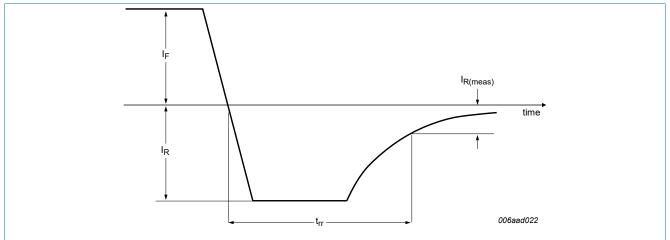


Fig. 14. Reverse recovery definition; step recovery

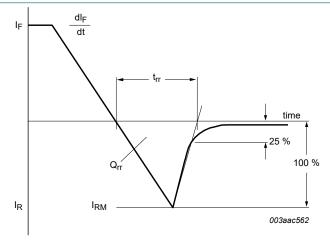


Fig. 15. Reverse recovery definition; ramp recovery

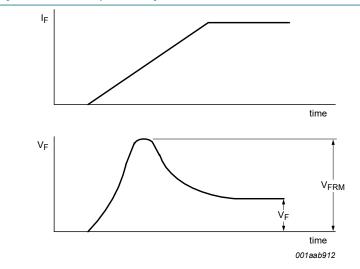
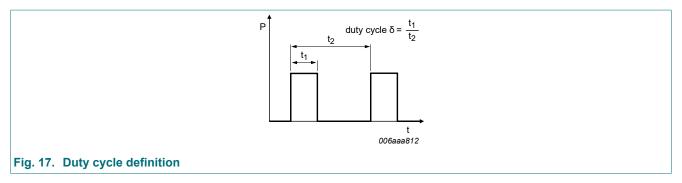


Fig. 16. Forward recovery definition



The current ratings for the typical waveforms are calculated according to the equations:

 $I_{F(AV)}=I_M\times\delta$  with  $I_M$  defined as peak current

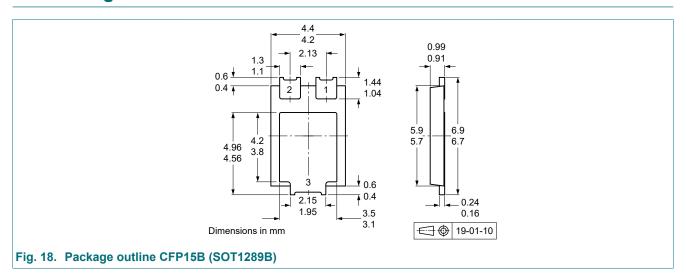
 $I_{RMS} = I_{F(AV)}$  at DC, and  $I_{RMS} = I_{M} \times \sqrt{\delta}$ 

with I<sub>RMS</sub> defined as RMS current.

### **Quality information**

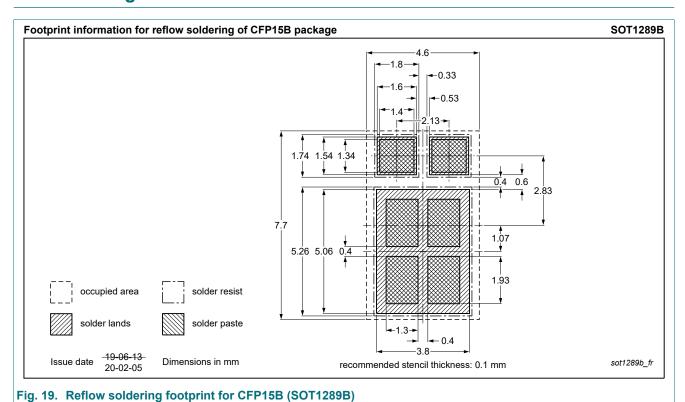
This product has been qualified in accordance with the Automotive Electronics Council (AEC) standard Q101 - Stress test qualification for discrete semiconductors, and is suitable for use in automotive applications.

## 12. Package outline



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## 13. Soldering



## 14. Revision history

### **Table 8. Revision history**

| Data sheet ID       | Release date      | Data sheet status    | Change notice | Supersedes          |
|---------------------|-------------------|----------------------|---------------|---------------------|
| PMEG060T080CLPE v.2 | 20200427          | Product data sheet   | -             | PMEG060T080CLPE v.1 |
| Modifications:      | Product status of | changed              |               |                     |
| PMEG060T080CLPE v.1 | 20200304          | Objective data sheet | -             | -                   |

## 15. Legal information

#### Data sheet status

| Document status [1][2]         | Product<br>status [3] | Definition  |
|--------------------------------|-----------------------|---|
| Objective [short] data sheet   | Development           | This document contains data from the objective specification for product development. |
| Preliminary [short] data sheet | Qualification         | This document contains data from the preliminary specification.                       |
| Product [short]<br>data sheet  | Production            | This document contains the product specification.                                     |

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Date of release: 27 April 2020

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